

Abstract

Provided are an epoxy resin, a polyhydric hydroxy resin, and a composition thereof that produces a cured product of excellent flame retardancy, excellent moisture resistance, and low elasticity and is suitable for use in encapsulating electronic parts, circuit board materials, and the like. Disclosed is a styrene-modified polyhydric hydroxy resin that is produced by reacting 0.3 to 1.0 mole of a styrene with 1 mole of a phenol novolac in the presence of an acid catalyst and contains a monohydric hydroxy compound as a by-product in an amount of 3% or less by area when detected by gel permeation chromatography. Disclosed further are an epoxy resin that is produced by reacting the styrene-modified polyhydric hydroxy resin with epichlorohydrin and an epoxy resin composition that comprises the styrene-modified polyhydric hydroxy resin or the epoxy resin as an essential component.